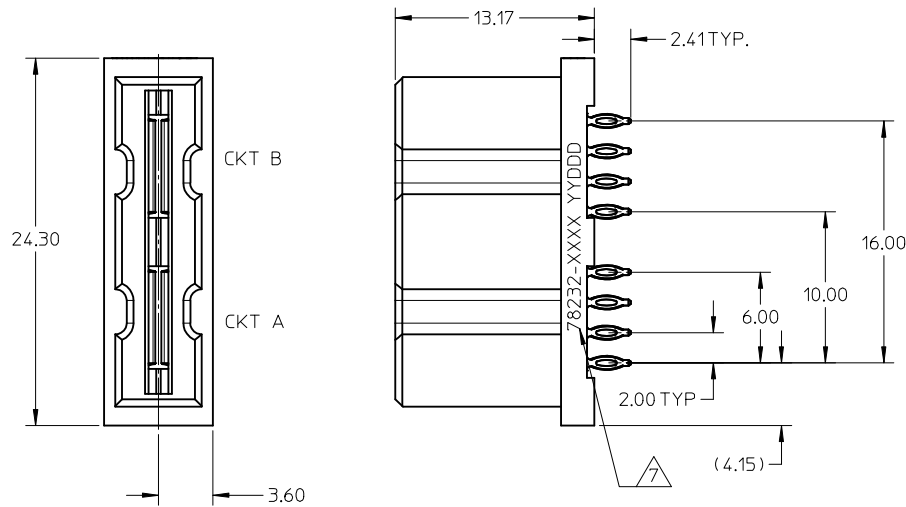
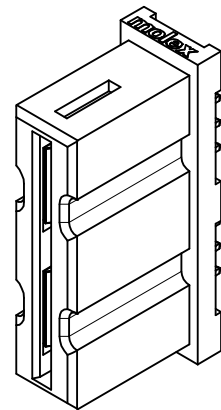
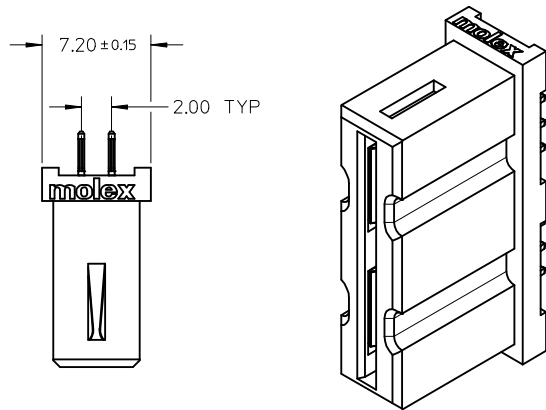


PART NUMBER	△ PLATING OPTION	PACKAGING
78232-1001	TIN PLATING	TRAY
78232-5001	TIN-LEAD PLATING	TRAY



NOTES

- MATERIALS :  
HOUSING - LCP, GLASS FILLED, UL94-V0, COLOR: BLACK.  
POWER PIN - COPPER ALLOY
- FINISHES :  
TIN OPTION - 0.76 MICROMETER MINIMUM GOLD AT CONTACT AREA AND 2.54 MICROMETER MINIMUM TIN AT SOLDER TAIL AREA OVER 1.27um MINIMUM NICKEL UNDERPLATE.  
TIN-LEAD OPTION - 0.76 MICROMETER MINIMUM GOLD AT CONTACT AREA AND 2.54 MICROMETER MINIMUM TIN-LEAD AT SOLDER TAIL AREA OVER 1.27um MINIMUM NICKEL UNDERPLATE.

- PRODUCT SPECIFICATION: PS-78231-006.
- COMPONENT STAY AWAY ZONE FROM CONNECTOR.
- PCB NOTE FOR PLATED HOLE.

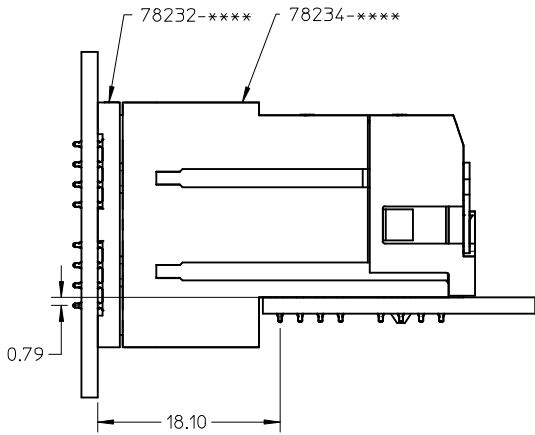
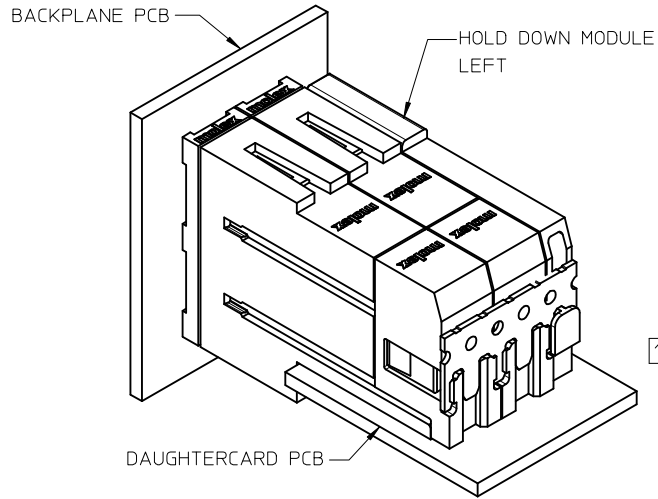
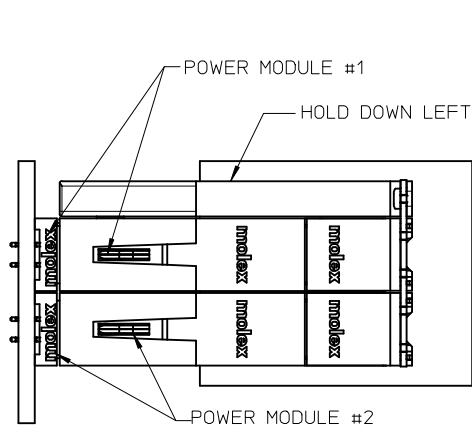
TYPE OF PLATED HOLE	DRILLED HOLE SIZE	PLATING THICKNESS	PLATED HOLE SIZE "Ø DIM H"
TIN/TIN-LEAD	0.838	0.007 MIN TIN/TIN-LEAD/SILVER	0.725 ± 0.075
SILVER	0.863	OVER 0.03 TO 0.08 COPPER PLATING	0.750 ± 0.050

SEE SHEET 2 FOR RECOMMENDED PCB LAYOUT.

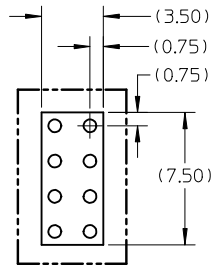
- MATES WITH 78234-\*\*\*\*.
- PART NUMBER AND YEAR-WK CODE.
- ADJACENT POWER MODULE PITCH.
- PACKAGING PROCEDURE AS PER PK-78232-001.

REVISED EC NO: S2009-0287 DRW: KJKOH 2008/11/27 CHK: ANG 2008/11/28 APPR: SHONG 2008/12/02 B3	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽=0 ∇=0	mm INCH	MM ONLY	NTS	METRIC		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± ---	DRAWN BY DATE SHONG 2006/08/15	TITLE	I-TRAC POWER, 11 ROW VERTICAL RECEPTACLE PRESS-FIT		
		ANGULAR ± 3 °	CHECKED BY DATE LNG 2006/08/25	APPROVED BY DATE NAGESHKN 2006/08/28	MOLEX INCORPORATED		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.	SEE TABLE	DOCUMENT NO.	SD-78232-001		
		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

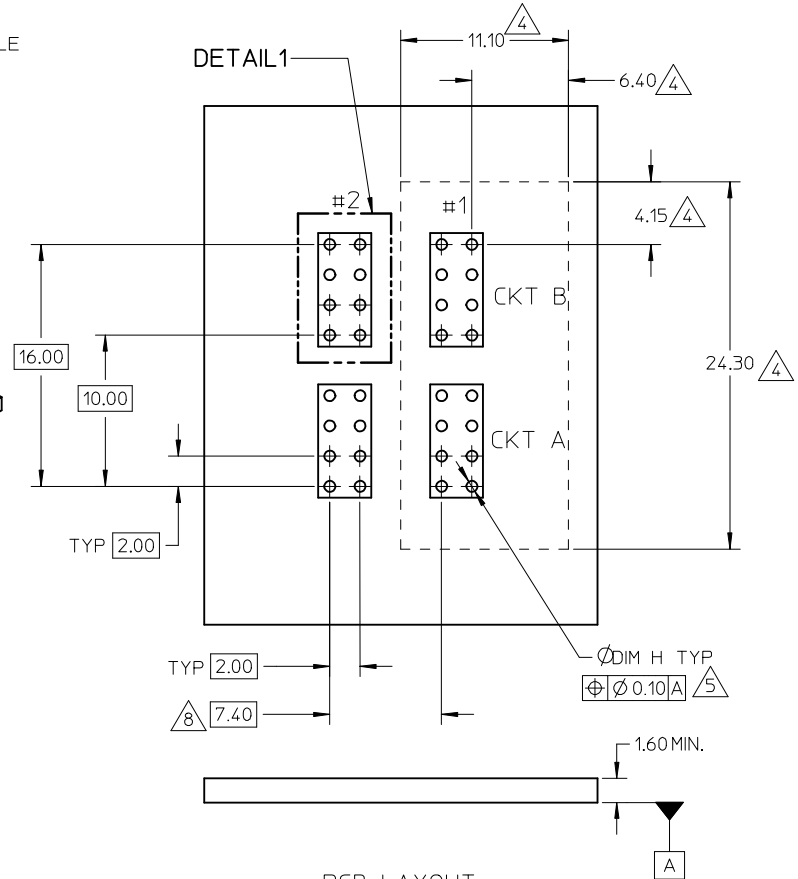
# MATED DIMENSIONS AND PCB LAYOUT WITH HEADER HOLD DOWN LEFT



MATED SYSTEM FOR 78232 & 78234



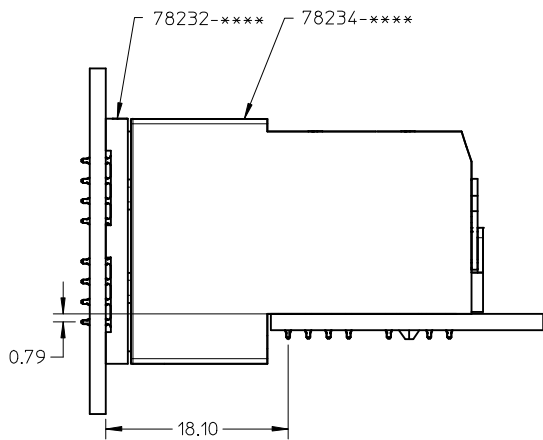
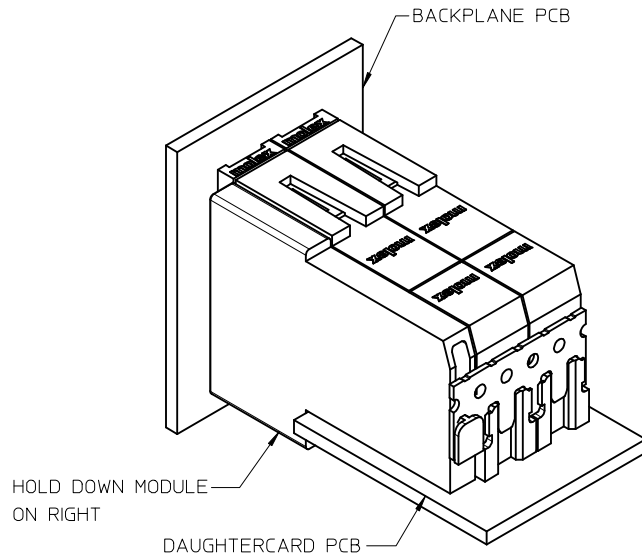
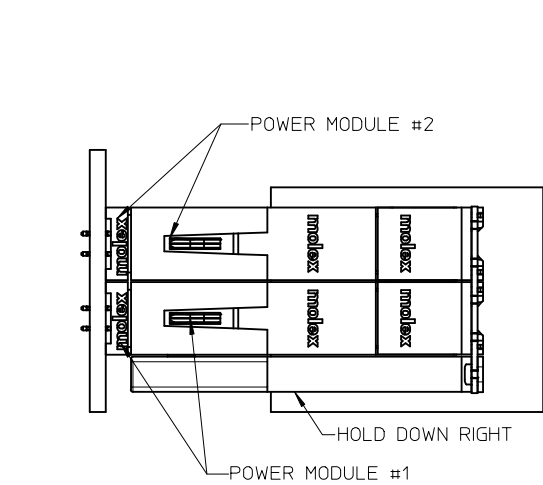
DETAIL1  
COPPER PAD REFERENCE



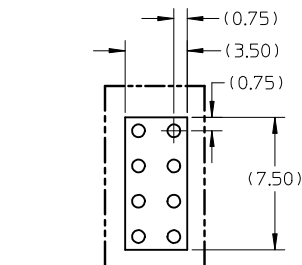
PCB LAYOUT  
(MATED WITH HEADER HOLD DOWN MODULE LEFT)  
COMPONENT SIDE SHOWN

REVISED EC NO: S2009-0287 DRWNK:JKH 2008/11/27 CHKD:ANG 2008/11/28 APPR:SHONG 2008/12/02 B3	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 3 °	DIMENSION STYLE MM ONLY DRAWN BY SHONG DATE 2006/08/15 CHECKED BY LNG DATE 2006/08/25 APPROVED BY NAGESHKN DATE 2006/08/28 MATERIAL NO.	SCALE NTS TITLE I-TRAC POWER, 11 ROW VERTICAL RECEPTACLE PRESS-FIT MOLEX INCORPORATED DOCUMENT NO. SD-78232-001	DESIGN UNITS METRIC THIRD ANGLE PROJECTION	SHEET NO. 2 OF 3	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
			SIZE A3				

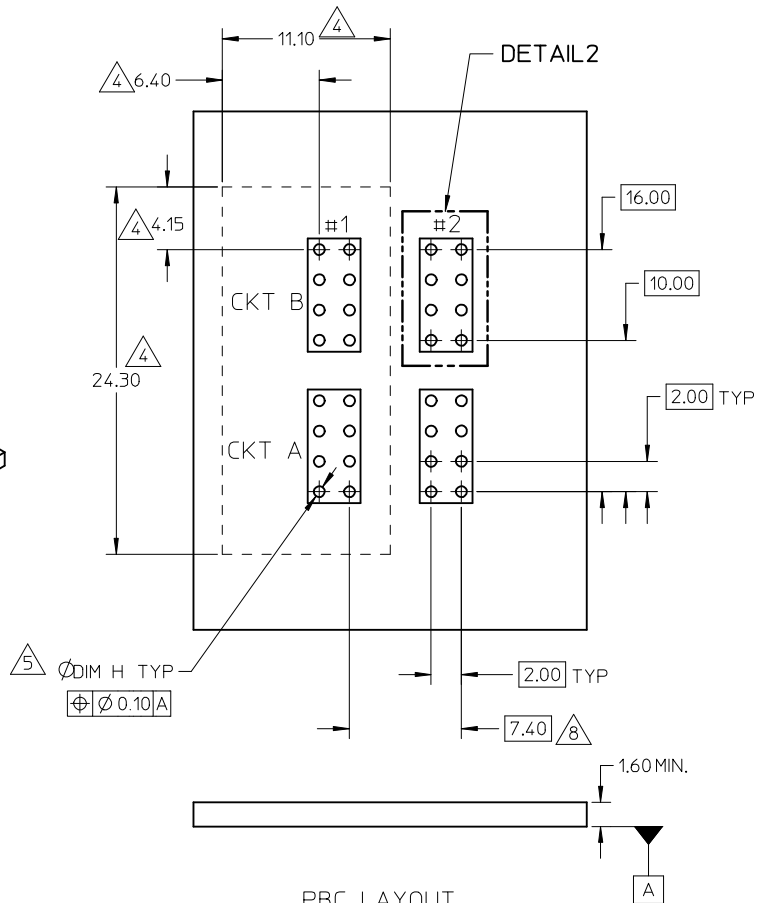
# MATED DIMENSIONS AND PCB LAYOUT WITH HEADER HOLD DOWN RIGHT



MATED SYSTEM FOR 78232 & 78234



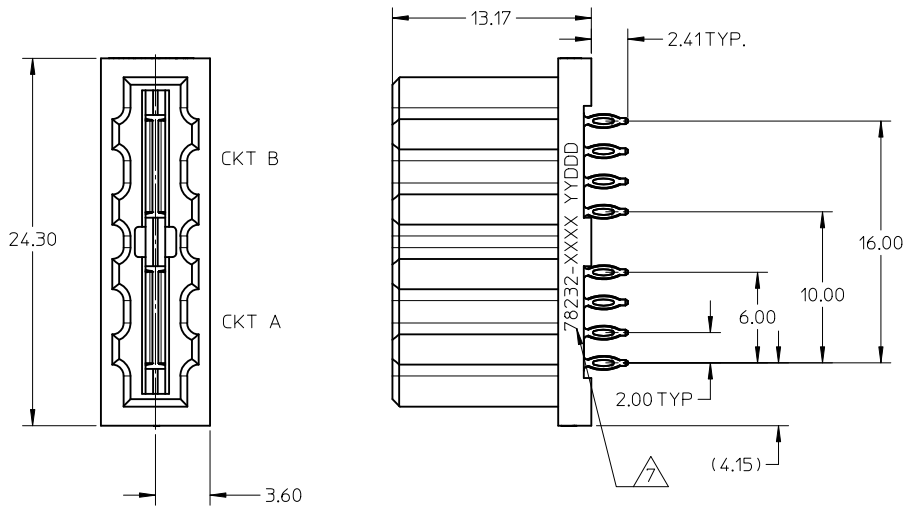
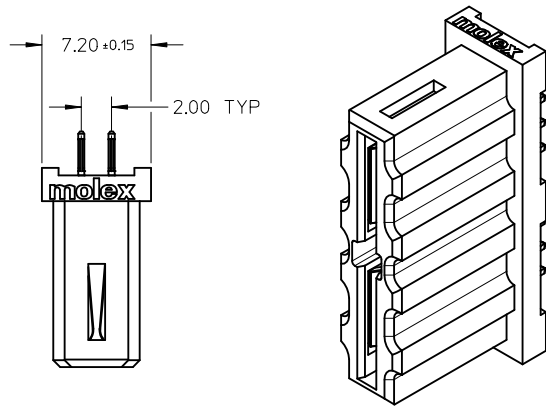
DETAIL2  
COPPER PAD REFERENCE



PBC LAYOUT  
(MATED WITH HEADER HOLD DOWN RIGHT)  
COMPONENT SIDE SHOWN

REVISED EC NO: S2009-0287 DRWNK:JKOH 2008/11/27 CHKD:ANG 2008/11/28 APPR:SHONG 2008/12/02 REV B3	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▼=0 C=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 3 °	MM ONLY	NTS	METRIC		
	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY SHONG CHECKED BY LNG APPROVED BY NAGESHKN MATERIAL NO. SEE TABLE	DATE 2006/08/15 DATE 2006/08/25 DATE 2006/08/28	TITLE	I-TRAC POWER, 11 ROW VERTICAL RECEPTACLE PRESS-FIT	
					MOLEX INCORPORATED DOCUMENT NO. SD-78232-001	SHEET NO. 3 OF 3	

PART NUMBER	△ 2 PLATING OPTION	PACKAGING
78232-1001	TIN PLATING	TRAY
78232-5001	TIN-LEAD PLATING	TRAY



NOTES

- MATERIALS :  
HOUSING - LCP, GLASS FILLED, UL94-V0, COLOR: BLACK.  
POWER PIN - COPPER ALLOY
- FINISHES :  
TIN OPTION - 0.76 MICROMETER MINIMUM GOLD AT CONTACT AREA AND 2.54 MICROMETER MINIMUM TIN AT SOLDER TAIL AREA OVER 1.27 μm MINIMUM NICKEL UNDERPLATE.  
TIN-LEAD OPTION - 0.76 MICROMETER MINIMUM GOLD AT CONTACT AREA AND 2.54 MICROMETER MINIMUM TIN-LEAD AT SOLDER TAIL AREA OVER 1.27 μm MINIMUM NICKEL UNDERPLATE.
- PRODUCT SPECIFICATION: PS-78231-006.
- COMPONENT STAY AWAY ZONE FROM CONNECTOR.
- PCB NOTE FOR PLATED HOLE.

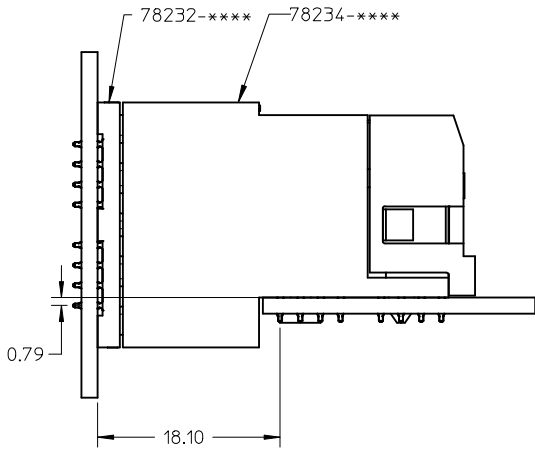
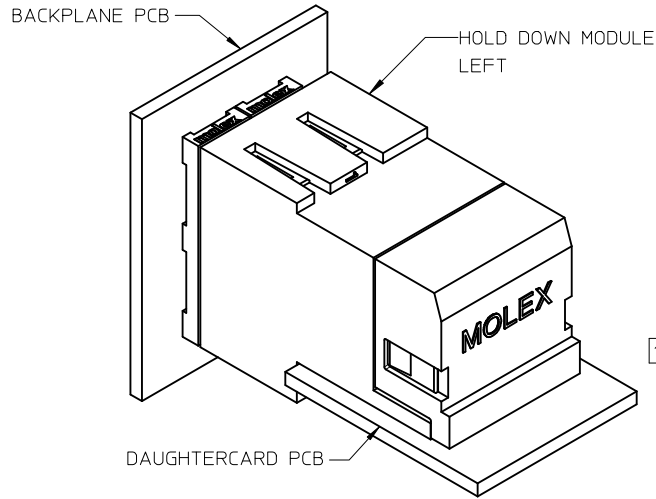
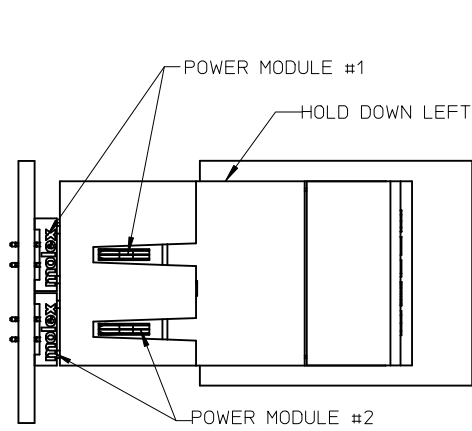
TYPE OF PLATED HOLE	DRILLED HOLE SIZE	PLATING THICKNESS	PLATED HOLE SIZE "ØDIM H"
TIN/TIN-LEAD	0.838	0.007 MIN TIN/TIN-LEAD/SILVER	0.725 ± 0.075
SILVER	0.863	OVER 0.03 TO 0.08 COPPER PLATING	0.750 ± 0.050

SEE SHEET 2 FOR RECOMMENDED PCB LAYOUT.

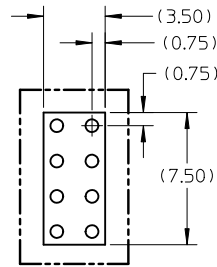
- MATES WITH 78234-\*\*\*\*.
- PART NUMBER AND YEAR-WK CODE.
- ADJACENT POWER MODULE PITCH.
- PACKAGING PROCEDURE AS PER PK-78232-001.

REV CORING DESIGN EC NO: S2012-0478 DRWN: SHONG 2011/11/25 CHKD: LNG 2012/01/06 APPR: NAGESHKN 2012/01/06	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽=0 ∠=0	mm INCH	MM ONLY	NTS	METRIC		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± ---	DRAWN BY DATE SHONG 2006/08/15	I-TRAC POWER, 11 ROW VERTICAL RECEPTACLE PRESS-FIT MOLEX INCORPORATED			
		ANGULAR ± 3 °	CHECKED BY DATE LNG 2006/08/25				
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPROVED BY DATE NAGESHKN 2012/01/06	MOLEX INCORPORATED SD-78232-011				
		MATERIAL NO.	SEE TABLE	DOCUMENT NO.	SHEET NO. 1 OF 3		

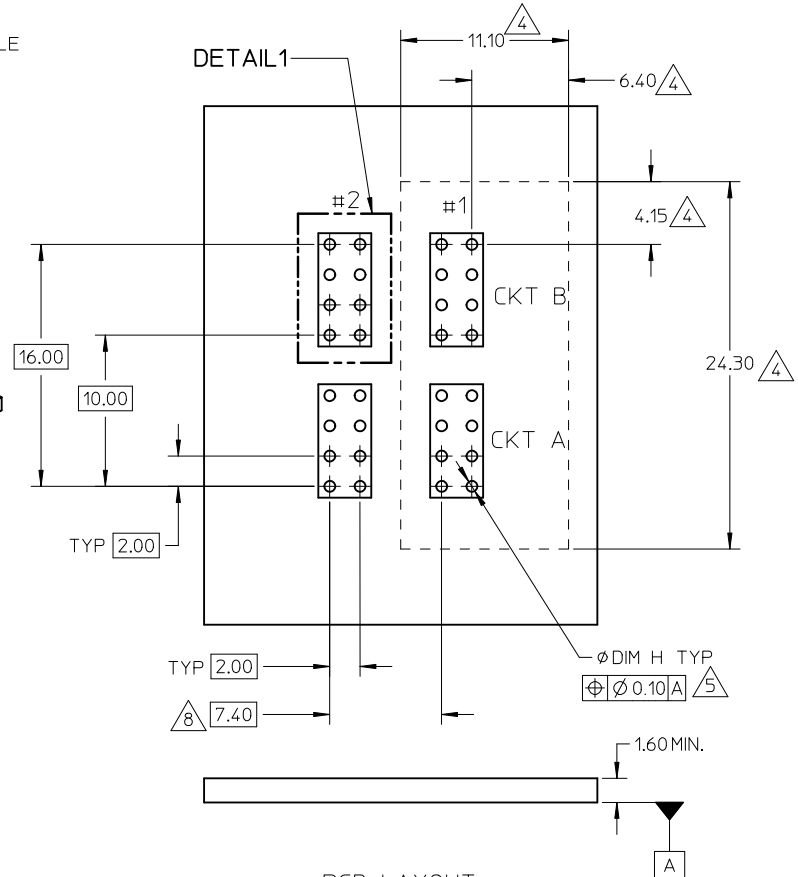
# MATED DIMENSIONS AND PCB LAYOUT WITH HEADER HOLD DOWN LEFT



MATED SYSTEM FOR 78232 & 78234



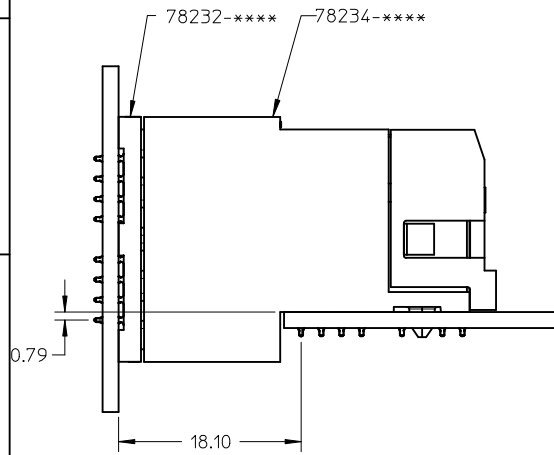
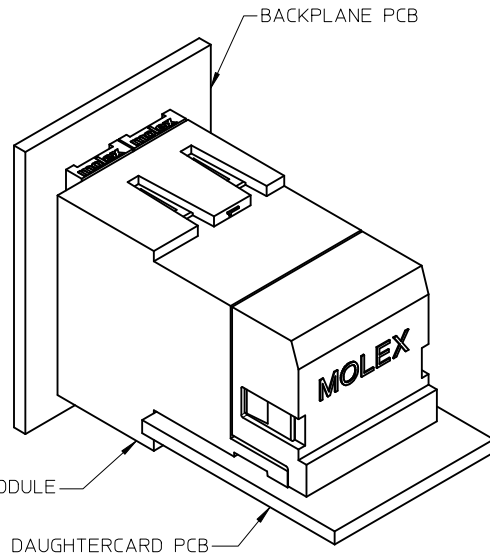
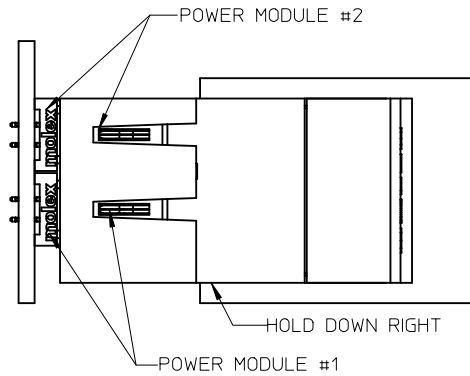
DETAIL1  
COPPER PAD REFERENCE



PCB LAYOUT  
(MATED WITH HEADER HOLD DOWN MODULE LEFT)  
COMPONENT SIDE SHOWN

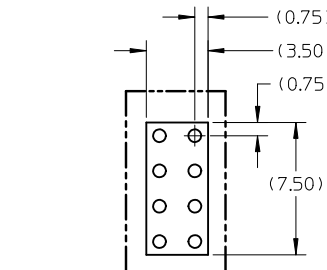
<b>REV CORING DESIGN</b> EC NO: S2012-0428 DRWN: SHONG 2011/11/25 CHKD: LNG 2012/01/06 APPR: NAGESHKN 2012/01/06	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	SHONG	2006/08/15	I-TRAC POWER, 11 ROW VERTICAL RECEPTACLE PRESS-FIT			
		3 PLACES	± ---	± ---	CHECKED BY	DATE				
2 PLACES	± 0.25	± ---	LNG	2006/08/25	MOLEX INCORPORATED					
1 PLACE	± ---	± ---	APPROVED BY	DATE						
	ANGULAR ± 3 °		NAGESHKN	2012/01/06	MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-78232-011		2 OF 3			
			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

# MATED DIMENSIONS AND PCB LAYOUT WITH HEADER HOLD DOWN RIGHT

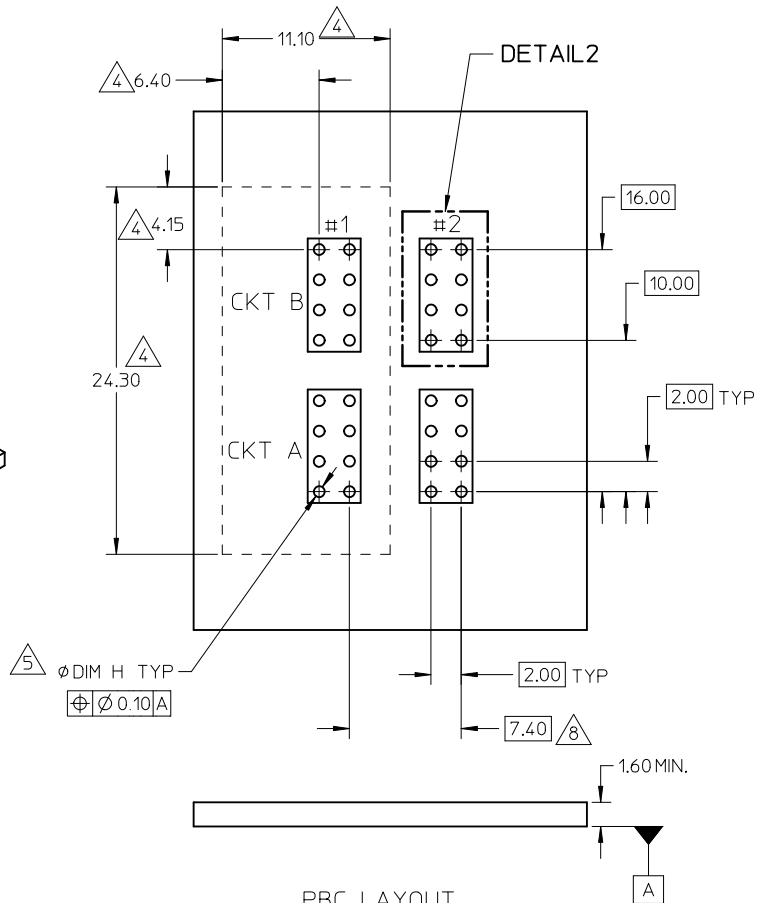


MATED SYSTEM FOR 78232 & 78234

HOLD DOWN MODULE ON RIGHT



DETAIL2  
COPPER PAD REFERENCE



PBC LAYOUT  
(MATED WITH HEADER HOLD DOWN RIGHT)  
COMPONENT SIDE SHOWN

REV CORING DESIGN EC NO: S2012-0428 DRWN: SHONG CHKD: LNG APPR: NAGESHKN	DESCRIPTION 2011/11/25 2012/01/06 2012/01/06	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
			mm	INCH	MM ONLY	NTS	METRIC		
			4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE	I-TRAC POWER, 11 ROW VERTICAL RECEPTACLE PRESS-FIT
			3 PLACES	± ---	± ---	SHONG	2006/08/15		
2 PLACES	± 0.25	± ---	CHECKED BY	DATE		MOLEX INCORPORATED			
1 PLACE	± ---	± ---	LNG	2006/08/25					
ANGULAR ± 3 °			APPROVED BY		DATE				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			NAGESHKN		2012/01/06				
MATERIAL NO.			SEE TABLE						
SIZE			A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				